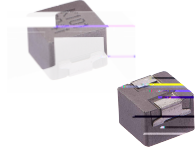


MDA HT Series

SMD Low Profile High Current Molded Inductor

Size 7054



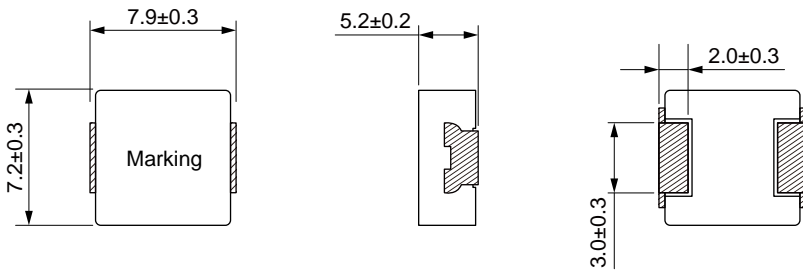
FEATURES

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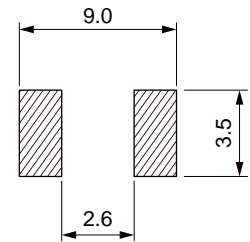
APPLICATION

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Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

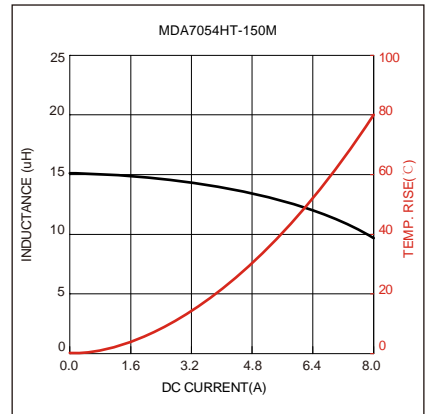
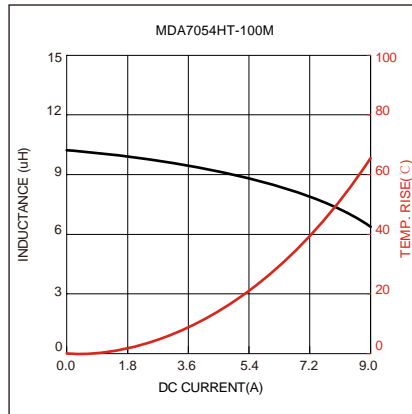
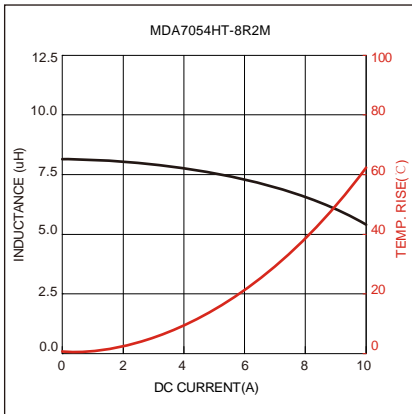
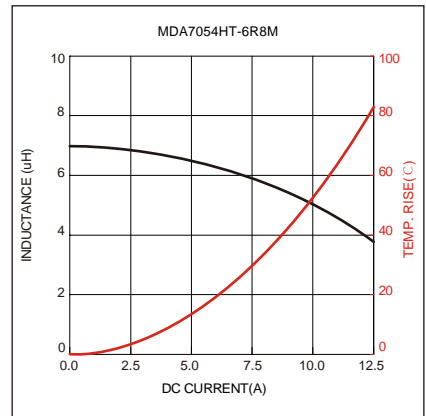
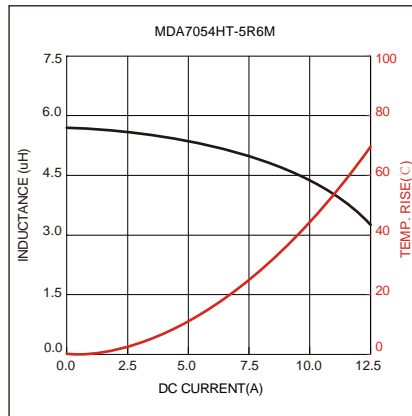
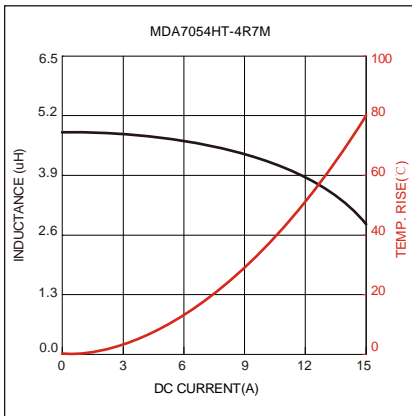
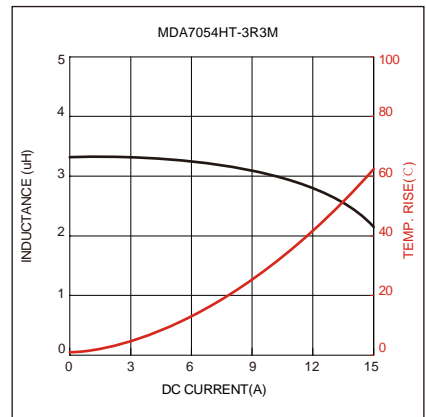
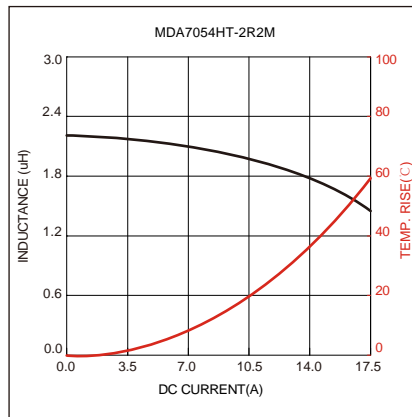
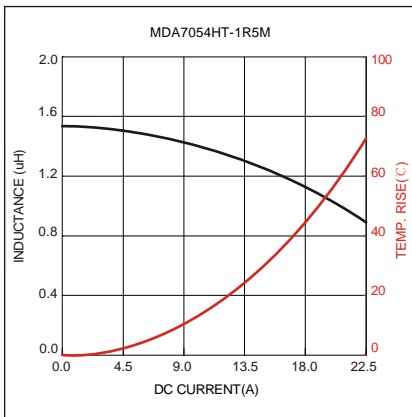
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.

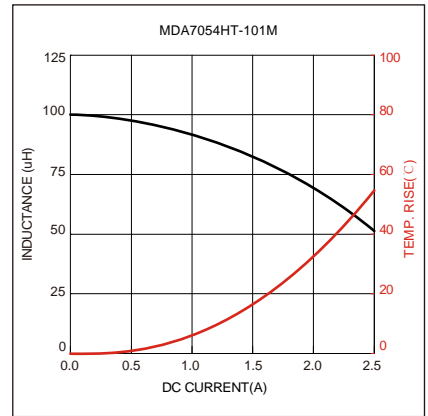
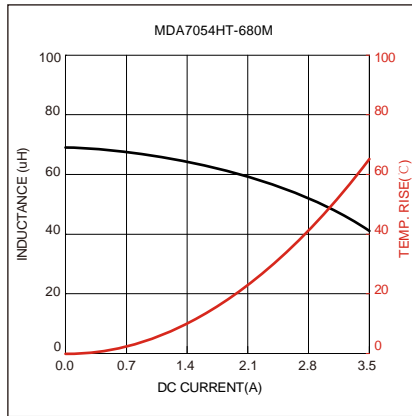
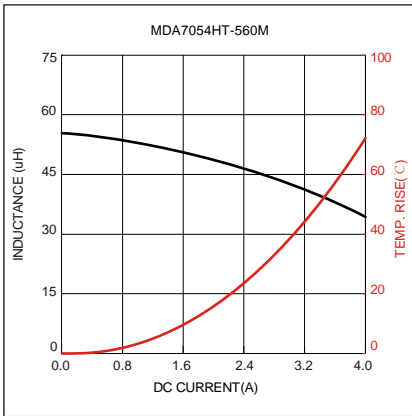
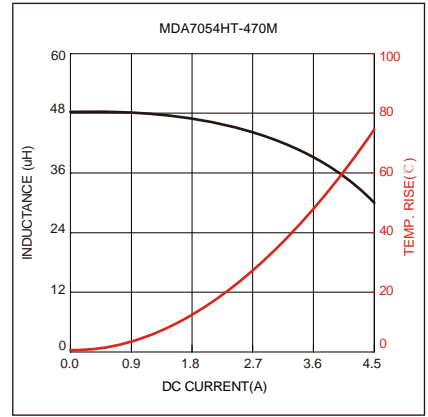
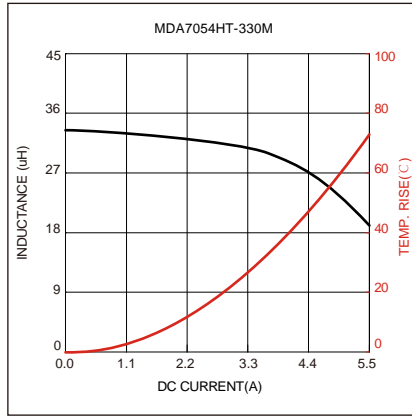
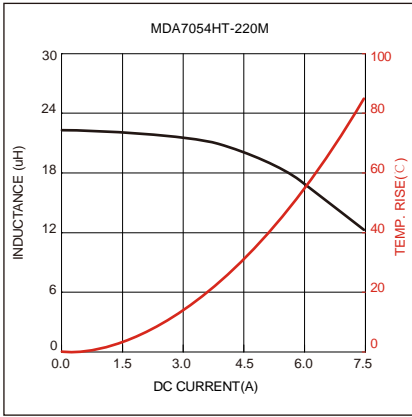
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Current Typ. (A)	Current Max. (A)	DC Resistance Typ.	DC Resistance Max.

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is $\Delta T=40^{\circ}\text{C}$

Typical Electrical Characteristics:





Soldering Reflow:

Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C : 60~90 sec.

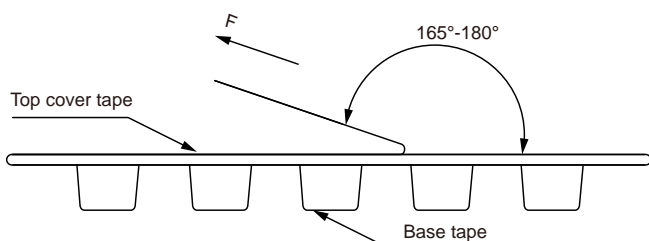
Max temperature: 260°C .

Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Peel force of top cover tape:

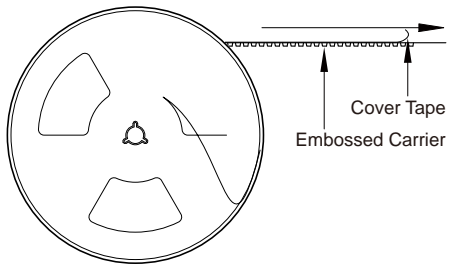


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing (Inductance+period)
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Reel Dimension: [mm]



Packaging Quantity: